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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Ritzdorf et al.

For: Method for Filling Recessed Micro-
Structures with Metallization in the
Production of a Microelectronic Device

Serial No.: 09/018,783

Filed: February 4, 1998

Examiner: (not assigned)

Art Unit: 1763

CERTIFICATE OF MAILING

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Washington, D.C. 20231

Dear Sir:

Consistent with the correspondence address identified in the executed declaration
filed herewith, please change the Correspondence Address for the above-identified
application to:

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Respectfully submitted,

BY

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